

REMARKS

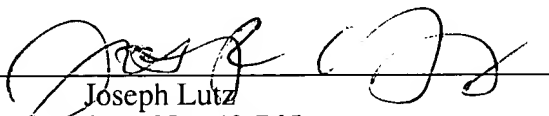
No new matter has been added to the claims. Claims 1-8 have been canceled and Claims 9 and 13 have been amended to more accurately define the invention disclosed in the Continuation Patent Application of the patent application as filed on June 18, 1999.

In view of the foregoing, it is believed that all claims now pending are now in condition for allowance and such action is earnestly solicited at the earliest possible date. If there are any fees due in connection with the filing of this response, please charge those fees to our Deposit Account No. 02-2666. Questions regarding this matter should be directed to the undersigned at (310) 207-3800.

Respectfully submitted,
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Dated June 28, 2002

By: _____


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VERSION MARKED TO REFLECT CHANGES

9. (Amended) A method for decapsulating an integrated circuit (IC) package ~~that is mounted to a printed circuit board~~, comprising ~~the steps of:~~

receiving the IC package installed onto a printed circuit board via one of a through-hole attachment and a surface-mount attachment;

- a) ~~providing an injection head that sprays a decapsulation fluid;~~
- b) ~~placing the printed circuit board installed IC package onto a tray;~~
- e) ~~clamping said an injection head onto the installed IC integrated circuit package; and,~~
- d) ~~spraying, via the injection head, the decapsulation fluid onto the installed IC integrated circuit package.~~

13. (Amended) A method for decapsulating an integrated circuit (IC) package ~~that is mounted to a first surface of a printed circuit board, the printed circuit board having a second surface located below the first surface of the printed circuit board~~, comprising ~~the step of:~~

receiving the IC package installed onto a first surface of a printed circuit board, via one of a through-hole attachment and a surface-mount attachment, wherein the printed circuit board includes a second surface located below the first surface of the printed circuit board;

spraying a decapsulation fluid onto the installed IC integrated circuit package via an injection head clamped to the installed IC integrated circuit package, ~~said the~~ injection head having a nozzle disposed above the ~~integrated circuit~~ installed IC package that is in fluid communication with an inlet port of said injection head, and a return port that is in fluid communication with an outlet port of ~~said the~~ injection head.